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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	20 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	30
Number of Macrocells	480
Number of Gates	10000
Number of I/O	146
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP Exposed Pad
Supplier Device Package	208-RQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm9480rc208-20

…and More Features

- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable security bit for protection of proprietary designs
- Software design support and automatic place-and-route provided by Altera's MAX+PLUS® II development system on Windows-based PCs as well as Sun SPARCstation, HP 9000 Series 700/800, and IBM RISC System/6000 workstations
- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, and VeriBest
- Programming support with Altera's Master Programming Unit (MPU), BitBlaster™ serial download cable, ByteBlaster™ parallel port download cable, and ByteBlasterMV™ parallel port download cable, as well as programming hardware from third-party manufacturers
- Offered in a variety of package options with 84 to 356 pins (see Table 2)

Table 2. MAX 9000 Package Options & I/O Counts *Note (1)*

Device	84-Pin PLCC	208-Pin RQFP	240-Pin RQFP	280-Pin PGA	304-Pin RQFP	356-Pin BGA
EPM9320	60 *(2)*	132	–	168	–	168
EPM9320A	60 *(2)*	132	–	–	–	168
EPM9400	59 *(2)*	139	159	–	–	–
EPM9480	–	146	175	–	–	–
EPM9560	–	153	191	216	216	216
EPM9560A	–	153	191	–	–	216

Notes:

(1) MAX 9000 device package types include plastic J-lead chip carrier (PLCC), power quad flat pack (RQFP), ceramic pin-grid array (PGA), and ball-grid array (BGA) packages.

(2) Perform a complete thermal analysis before committing a design to this device package. See *Application Note 74 (Evaluating Power for Altera Devices)*.

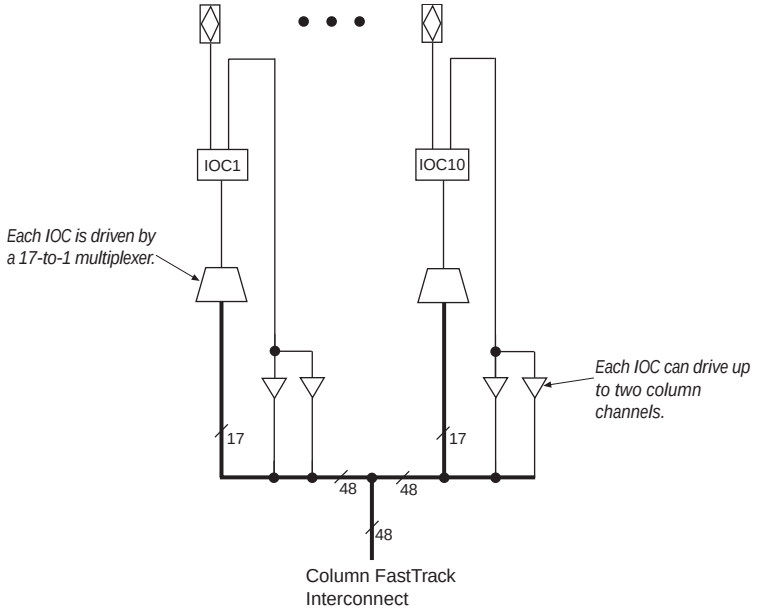
All MAX 9000 device packages provide four dedicated inputs for global control signals with large fan-outs. Each I/O pin has an associated I/O cell register with a clock enable control on the periphery of the device. As outputs, these registers provide fast clock-to-output times; as inputs, they offer quick setup times.

MAX 9000 EPLDs provide 5.0-V in-system programmability (ISP). This feature allows the devices to be programmed and reprogrammed on the printed circuit board (PCB) for quick and efficient iterations during design development and debug cycles. MAX 9000 devices are guaranteed for 100 program and erase cycles.

MAX 9000 EPLDs contain 320 to 560 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND / fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. For increased flexibility, each macrocell offers a dual-output structure that allows the register and the product terms to be used independently. This feature allows register-rich and combinatorial-intensive designs to be implemented efficiently. The dual-output structure of the MAX 9000 macrocell also improves logic utilization, thus increasing the effective capacity of the devices. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 9000 family provides programmable speed / power optimization. Speed-critical portions of a design can run at high speed / full power, while the remaining portions run at reduced speed / low power. This speed / power optimization feature enables the user to configure one or more macrocells to operate at 50% or less power while adding only a nominal timing delay. MAX 9000 devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. MAX 9000 devices offer the MultiVolt feature, which allows output drivers to be set for either 3.3-V or 5.0-V operation in mixed-voltage systems.

Figure 9. MAX 9000 Column-to-IOC Connections



Dedicated Inputs

In addition to the general-purpose I/O pins, MAX 9000 devices have four dedicated input pins. These dedicated inputs provide low-skew, device-wide signal distribution to the LABs and IOCs in the device, and are typically used for global clock, clear, and output enable control signals. The global control signals can feed the macrocell or IOC clock and clear inputs, as well as the IOC output enable. The dedicated inputs can also be used as general-purpose data inputs because they can feed the row FastTrack Interconnect (see Figure 2 on page 7).

I/O Cells

Figure 10 shows the IOC block diagram. Signals enter the MAX 9000 device from either the I/O pins that provide general-purpose input capability or from the four dedicated inputs. The IOCs are located at the ends of the row and column interconnect channels.

The VCCIO pins can be connected to either a 3.3-V or 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V power supply, the output levels are compatible with 5.0-V systems. When the VCCIO pins are connected to a 3.3-V power supply, the output high is at 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1}.

In-System Programmability (ISP)

MAX 9000 devices can be programmed in-system through a 4-pin JTAG interface. ISP offers quick and efficient iterations during design development and debug cycles. The MAX 9000 architecture internally generates the 12.0-V programming voltage required to program EEPROM cells, eliminating the need for an external 12.0-V power supply to program the devices on the board. During ISP, the I/O pins are tri-stated to eliminate board conflicts.

ISP simplifies the manufacturing flow by allowing the devices to be mounted on a printed circuit board with standard pick-and-place equipment before they are programmed. MAX 9000 devices can be programmed by downloading the information via in-circuit testers, embedded processors, or the Altera BitBlaster, ByteBlaster, or ByteBlasterMV download cable. (The ByteBlaster cable is obsolete and has been replaced by the ByteBlasterMV cable, which can interface with 2.5-V, 3.3-V, and 5.0-V devices.) Programming the devices after they are placed on the board eliminates lead damage on high pin-count packages (e.g., QFP packages) due to device handling. MAX 9000 devices can also be reprogrammed in the field (i.e., product upgrades can be performed in the field via software or modem).

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. Because some in-circuit testers platforms have difficulties supporting an adaptive algorithm, Altera offers devices tested with a constant algorithm. Devices tested to the constant algorithm have an “F” suffix in the ordering code.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 9000 device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

1. *Enter ISP.* The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.

2. *Check ID.* Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.

3. *Bulk Erase.* Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.

4. *Program.* Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.

5. *Verify.* Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.

6. *Exit ISP.* An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

The programming times described in Tables 7 through 9 are associated with the worst-case method using the ISP algorithm.

Table 7. MAX 9000 t_{PULSE} & $Cycle_{TCK}$ Values

Device	Programming		Stand-Alone Verification	
	t_{PPULSE} (s)	$Cycle_{PTCK}$	t_{VPULSE} (s)	$Cycle_{VTCK}$
EPM9320 EPM9320A	11.79	2,966,000	0.15	1,806,000
EPM9400	12.00	3,365,000	0.15	2,090,000
EPM9480	12.21	3,764,000	0.15	2,374,000
EPM9560 EPM9560A	12.42	4,164,000	0.15	2,658,000

Tables 8 and 9 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 8. MAX 9000 In-System Programming Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM9320 EPM9320A	12.09	12.38	13.27	14.76	17.72	26.62	41.45	71.11	s
EPM9400	12.34	12.67	13.68	15.37	18.73	28.83	45.65	79.30	s
EPM9480	12.59	12.96	14.09	15.98	19.74	31.03	49.85	87.49	s
EPM9560 EPM9560A	12.84	13.26	14.50	16.59	20.75	33.24	54.06	95.70	s

Table 9. MAX 9000 Stand-Alone Verification Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM9320 EPM9320A	0.33	0.52	1.06	1.96	3.77	9.18	18.21	36.27	s
EPM9400	0.36	0.57	1.20	2.24	4.33	10.60	21.05	41.95	s
EPM9480	0.39	0.63	1.34	2.53	4.90	12.02	23.89	47.63	s
EPM9560 EPM9560A	0.42	0.69	1.48	2.81	5.47	13.44	26.73	53.31	s

Programming with External Hardware

MAX 9000 devices can be programmed on Windows-based PCs with an Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs continuity checking to ensure adequate electrical contact between the adapter and the device.

For more information, see the *Altera Programming Hardware Data Sheet*.

The MAX+PLUS II software can use text- or waveform-format test vectors created with the MAX+PLUS II Text Editor or Waveform Editor to test a programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 9000 device with the results of simulation.

Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.

For more information, see *Programming Hardware Manufacturers.*

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 9000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. Table 10 describes the JTAG instructions supported by the MAX 9000 family. The pin-out tables starting on page 38 show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 10. MAX 9000 JTAG Instructions

JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	Places the 1-bit bypass register between the `TDI` and `TDO` pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	Selects the IDCODE register and places it between `TDI` and `TDO`, allowing the IDCODE to be shifted out of `TDO`. Supported by the EPM9320A, EPM9400, EPM9480, and EPM9560A devices only.
UESCODE	Selects the user electronic signature (UESCODE) register and allows the UESCODE to be shifted out of `TDO` serially. This instruction is supported by MAX 9000A devices only.
ISP Instructions	These instructions are used when programming MAX 9000 devices via the JTAG ports with the BitBlaster or ByteBlasterMV download cable, or using a Jam File (**.jam**), Jam Byte-Code File (**.jbc**), or Serial Vector Format (**.svf**) File via an embedded processor or test equipment.

Operating Conditions

Tables 14 through 20 provide information on absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for MAX 9000 devices.

Table 14. MAX 9000 Device Absolute Maximum Ratings *Note (1)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply voltage	With respect to ground *(2)*	–2.0	7.0	V
V_I	DC input voltage		–2.0	7.0	V
V_{CCISP}	Supply voltage during in-system programming		–2.0	7.0	V
I_{OUT}	DC output current, per pin		–25	25	mA
T_{STG}	Storage temperature	No bias	–65	150	° C
T_{AMB}	Ambient temperature	Under bias	–65	135	° C
T_J	Junction temperature	Ceramic packages, under bias		150	° C
		PQFP and RQFP packages, under bias		135	° C

Table 15. MAX 9000 Device Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	*(3)*, *(4)*	4.75 (4.50)	5.25 (5.50)	V
V_{CCIO}	Supply voltage for output drivers, 5.0-V operation	*(3)*, *(4)*	4.75 (4.50)	5.25 (5.50)	V
	Supply voltage for output drivers, 3.3-V operation	*(3)*, *(4)*	3.00 (3.00)	3.60 (3.60)	V
V_{CCISP}	Supply voltage during in-system programming		4.75	5.25	V
V_I	Input voltage		–0.5	V_{CCINT} + 0.5	V
V_O	Output voltage		0	V_{CCIO}	V
T_A	Ambient temperature	For commercial use	0	70	° C
		For industrial use	–40	85	° C
T_J	Junction temperature	For commercial use	0	90	° C
		For industrial use	–40	105	° C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

Table 16. MAX 9000 Device DC Operating Conditions *Notes (5), (6)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{IH}	High-level input voltage	*(7)*	2.0	V_{CCINT} + 0.5	V
V_{IL}	Low-level input voltage		–0.5	0.8	V
V_{OH}	5.0-V high-level TTL output voltage	I_{OH} = –4 mA DC, V_{CCIO} = 4.75 V *(8)*	2.4		V
	3.3-V high-level TTL output voltage	I_{OH} = –4 mA DC, V_{CCIO} = 3.00 V *(8)*	2.4		V
	3.3-V high-level CMOS output voltage	I_{OH} = –0.1 mA DC, V_{CCIO} = 3.00 V *(8)*	V_{CCIO} – 0.2		V
V_{OL}	5.0-V low level TTL output voltage	I_{OL} = 12 mA DC, V_{CCIO} = 4.75 V *(8)*		0.45	V
	3.3-V low-level TTL output voltage	I_{OL} = 12 mA DC, V_{CCIO} = 3.00 V *(8)*		0.45	V
	3.3-V low-level CMOS output voltage	I_{OL} = 0.1 mA DC, V_{CCIO} = 3.00 V *(8)*		0.2	V
I_I	I/O pin leakage current of dedicated input pins	V_I = –0.5 to 5.5 V *(9)*	–10	10	µA
I_{OZ}	Tri-state output off-state current	V_I = –0.5 to 5.5 V	–40	40	µA

Table 17. MAX 9000 Device Capacitance: EPM9320, EPM9400, EPM9480 & EPM9560 Devices *Note (10)*

Symbol	Parameter	Conditions	Min	Max	Unit
C_{DIN1}	Dedicated input capacitance	V_{IN} = 0 V, f = 1.0 MHz		18	pF
C_{DIN2}	Dedicated input capacitance	V_{IN} = 0 V, f = 1.0 MHz		18	pF
C_{DIN3}	Dedicated input capacitance	V_{IN} = 0 V, f = 1.0 MHz		17	pF
C_{DIN4}	Dedicated input capacitance	V_{IN} = 0 V, f = 1.0 MHz		20	pF
$C_{I/O}$	I/O pin capacitance	V_{IN} = 0 V, f = 1.0 MHz		12	pF

Table 18. MAX 9000A Device Capacitance: EPM9320A & EPM9560A Devices *Note (10)*

Symbol	Parameter	Conditions	Min	Max	Unit
C_{DIN1}	Dedicated input capacitance	V_{IN} = 0 V, f = 1.0 MHz		16	pF
C_{DIN2}	Dedicated input capacitance	V_{IN} = 0 V, f = 1.0 MHz		10	pF
C_{DIN3}	Dedicated input capacitance	V_{IN} = 0 V, f = 1.0 MHz		10	pF
C_{DIN4}	Dedicated input capacitance	V_{IN} = 0 V, f = 1.0 MHz		12	pF
$C_{I/O}$	I/O pin capacitance	V_{IN} = 0 V, f = 1.0 MHz		8	pF

Table 19. MAX 9000 Device Typical I_{CC} Supply Current Values

Symbol	Parameter	Conditions	EPM9320	EPM9400	EPM9480	EPM9560	Unit
I_{CC1}	I_{CC} supply current (low-power mode, standby, typical)	V_I = ground, no load *(11)*	106	132	140	146	mA

Timing Model

The continuous, high-performance FastTrack Interconnect ensures predictable performance and accurate simulation and timing analysis. This predictable performance contrasts with that of FPGAs, which use a segmented connection scheme and hence have unpredictable performance. Timing simulation and delay prediction are available with the MAX+PLUS II Simulator and Timing Analyzer, or with industry-standard EDA tools. The Simulator offers both pre-synthesis functional simulation to evaluate logic design accuracy and post-synthesis timing simulation with 0.1-ns resolution. The Timing Analyzer provides point-to-point timing delay information, setup and hold time prediction, and device-wide performance analysis.

The MAX 9000 timing model in Figure 14 shows the delays that correspond to various paths and functions in the circuit. This model contains three distinct parts: the macrocell, IOC, and interconnect, including the row and column FastTrack Interconnect and LAB local array paths. Each parameter shown in Figure 14 is expressed as a worst-case value in the internal timing characteristics tables in this data sheet. Hand-calculations that use the MAX 9000 timing model and these timing parameters can be used to estimate MAX 9000 device performance.

For more information on calculating MAX 9000 timing delays, see *Application Note 77 (Understanding MAX 9000 Timing)*.

Tables 21 through 24 show timing for MAX 9000 devices.

Table 21. MAX 9000 External Timing Characteristics *Note (1)*

Symbol	Parameter	Conditions		Speed Grade						Unit
				-10		-15		-20		
				Min	Max	Min	Max	Min	Max	
t_{PD1}	Row I/O pin input to row I/O pin output	C1 = 35 pF *(2)*			10.0		15.0		20.0	ns
t_{PD2}	Column I/O pin input to column I/O pin output	C1 = 35 pF *(2)*	EPM9320A		10.8					ns
			EPM9320				16.0		23.0	ns
			EPM9400				16.2		23.2	ns
			EPM9480				16.4		23.4	ns
			EPM9560A		11.4					ns
			EPM9560				16.6		23.6	ns
t_{FSU}	Global clock setup time for I/O cell			3.0		5.0		6.0		ns
t_{FH}	Global clock hold time for I/O cell			0.0		0.0		0.0		ns
t_{FCO}	Global clock to I/O cell output delay	C1 = 35 pF		1.0 *(3)*	4.8	1.0 *(3)*	7.0	1.0 *(3)*	8.5	ns
t_{CNT}	Minimum internal global clock period	*(4)*			6.9		8.5		10.0	ns
f_{CNT}	Maximum internal global clock frequency	*(4)*		144.9		117.6		100.0		MHz

Table 22. MAX 9000 Internal Timing Characteristics *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-10		-15		-20		
			Min	Max	Min	Max	Min	Max	
t_{LAD}	Logic array delay			3.5		4.0		4.5	ns
t_{LAC}	Logic control array delay			3.5		4.0		4.5	ns
t_{IC}	Array clock delay			3.5		4.0		4.5	ns
t_{EN}	Register enable time			3.5		4.0		4.5	ns
t_{SEXP}	Shared expander delay			3.5		5.0		7.5	ns
t_{PEXP}	Parallel expander delay			0.5		1.0		2.0	ns
t_{RD}	Register delay			0.5		1.0		1.0	ns
t_{COMB}	Combinatorial delay			0.4		1.0		1.0	ns
t_{SU}	Register setup time		2.4		3.0		4.0		ns
t_{H}	Register hold time		2.0		3.5		4.5		ns
t_{PRE}	Register preset time			3.5		4.0		4.5	ns
t_{CLR}	Register clear time			3.7		4.0		4.5	ns
t_{FTD}	FastTrack drive delay			0.5		1.0		2.0	ns
t_{LPA}	Low-power adder	*(5)*		10.0		15.0		20.0	ns

Table 23. IOC Delays

Symbol	Parameter	Conditions	Speed Grade						Unit
			-10		-15		-20		
			Min	Max	Min	Max	Min	Max	
t_{IODR}	I/O row output data delay			0.2		0.2		1.5	ns
t_{IODC}	I/O column output data delay			0.4		0.2		1.5	ns
t_{IOC}	I/O control delay	*(6)*		0.5		1.0		2.0	ns
t_{IORD}	I/O register clock-to-output delay			0.6		1.0		1.5	ns
t_{IOCOMB}	I/O combinatorial delay			0.2		1.0		1.5	ns
t_{IOSU}	I/O register setup time before clock		2.0		4.0		5.0		ns
t_{IOH}	I/O register hold time after clock		1.0		1.0		1.0		ns
t_{IOCLR}	I/O register clear delay			1.5		3.0		3.0	ns
t_{IOFD}	I/O register feedback delay			0.0		0.0		0.5	ns
t_{INREG}	I/O input pad and buffer to I/O register delay			3.5		4.5		5.5	ns
t_{INCOMB}	I/O input pad and buffer to row and column delay			1.5		2.0		2.5	ns
t_{OD1}	Output buffer and pad delay, Slow slew rate = off, V_{CCIO} = 5.0 V	C1 = 35 pF		1.8		2.5		2.5	ns
t_{OD2}	Output buffer and pad delay, Slow slew rate = off, V_{CCIO} = 3.3 V	C1 = 35 pF		2.3		3.5		3.5	ns
t_{OD3}	Output buffer and pad delay, Slow slew rate = on, V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF		8.3		10.0		10.5	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		2.5		2.5		2.5	ns
t_{ZX1}	Output buffer enable delay, Slow slew rate = off, V_{CCIO} = 5.0 V	C1 = 35 pF		2.5		2.5		2.5	ns
t_{ZX2}	Output buffer enable delay, Slow slew rate = off, V_{CCIO} = 3.3 V	C1 = 35 pF		3.0		3.5		3.5	ns
t_{ZX3}	Output buffer enable delay, Slow slew rate = on, V_{CCIO} = 3.3 V or 5.0 V	C1 = 35 pF		9.0		10.0		10.5	ns

The parameters in this equation are shown below:

MC_{TON} = Number of macrocells with the Turbo Bit option turned on, as reported in the MAX+PLUS II Report File (**.rpt**)
MC_{DEV} = Number of macrocells in the device
MC_{USED} = Number of macrocells used in the design, as reported in the MAX+PLUS II Report File
$\mathbf{f_{MAX}}$ = Highest clock frequency to the device
$\mathbf{tog_{LC}}$ = Average percentage of logic cells toggling at each clock (typically 12.5%)
A, B, C = Constants, shown in Table 25

Table 25. MAX 9000 I_{CC} Equation Constants

Device	Constant A	Constant B	Constant C
EPM9320	0.81	0.33	0.056
EPM9320A	0.56	0.31	0.024
EPM9400	0.60	0.33	0.053
EPM9480	0.68	0.29	0.064
EPM9560	0.68	0.26	0.052
EPM9560A	0.56	0.31	0.024

This calculation provides an I_{CC} estimate based on typical conditions with no output load, using a typical pattern of a 16-bit, loadable, enabled up / down counter in each LAB. Actual I_{CC} values should be verified during operation, because the measurement is sensitive to the actual pattern in the device and the environmental operating conditions. Figure 15 shows typical supply current versus frequency for MAX 9000 devices.

Figure 15. I_{CC} vs. Frequency for MAX 9000 Devices (Part 1 of 2)

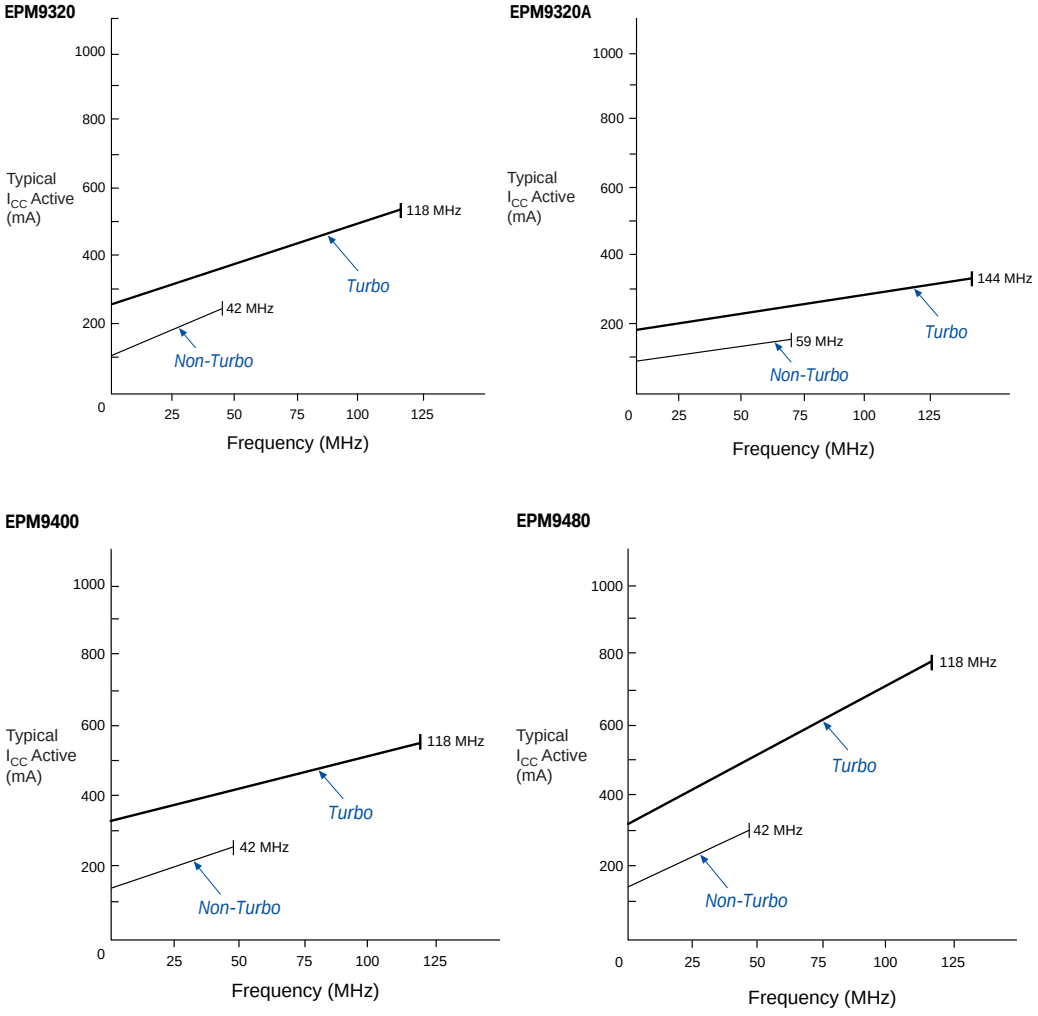
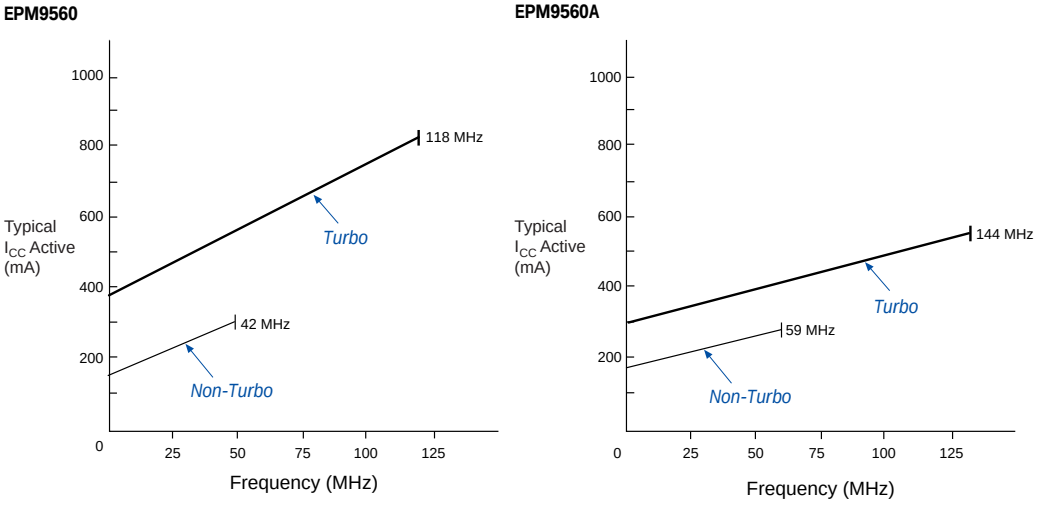


Figure 15. I_{CC} vs. Frequency for MAX 9000 Devices (Part 2 of 2)



Device Pin-Outs

Tables 26 through 29 show the dedicated pin names and numbers for each EPM9320, EPM9320A, EPM9400, EPM9480, EPM9560, and EPM9560A device package.

Table 26. EPM9320 & EPM9320A Dedicated Pin-Outs (Part 1 of 2) *Note (1)*

Pin Name	84-Pin PLCC *(2)*	208-Pin RQFP	280-Pin PGA *(3)*	356-Pin BGA
DIN1 (GCLK1)	1	182	V10	AD13
DIN2 (GCLK2)	84	183	U10	AF14
DIN3 (GCLR)	13	153	V17	AD1
DIN4 (GOE)	72	4	W2	AC24
TCK	43	78	A9	A18
TMS	55	49	D6	E23
TDI	42	79	C11	A13
TDO	30	108	A18	D3

Table 26. EPM9320 & EPM9320A Dedicated Pin-Outs (Part 2 of 2) *Note (1)*

Pin Name	84-Pin PLCC *(2)*	208-Pin RQFP	280-Pin PGA *(3)*	356-Pin BGA
GND	6, 18, 24, 25, 48, 61, 67, 70	14, 20, 24, 31, 35, 41, 42, 43, 44, 46, 47, 66, 85, 102, 110, 113, 114, 115, 116, 118, 121, 122, 132, 133, 143, 152, 170, 189, 206	D4, D5, D16, E4, E5, E6, E15, E16, F5, F15, G5, G15, H5, H15, J5, J15, K5, K15, L5, L15, M5, M15, N5, N15, P4, P5, P15, P16, R4, R5, R15, R16, T4, T5, T16	A9, A22, A25, A26, B25, B26, D2, E1, E26, F2, G1, G25, G26, H2, J1, J25, J26, K2, L26, M26, N1, N25, P26, R2, T1, U2, U26, V1, V25, W25, Y26, AA2, AB1, AB26, AC26, AE1, AF1, AF2, AF4, AF7, AF20
VCCINT (5.0 V only)	14, 21, 28, 57, 64, 71	10, 19, 30, 45, 112, 128, 139, 148	D15, E8, E10, E12, E14, R7, R9, R11, R13, R14, T14	D26, F1, H1, K26, N26, P1, U1, W26, AE26, AF25, AF26
VCCIO (3.3 or 5.0 V)	15, 37, 60, 79	5, 25, 36, 55, 72, 91, 111, 127, 138, 159, 176, 195	D14, E7, E9, E11, E13, R6, R8, R10, R12, T13, T15	A1, A2, A21, B1, B10, B24, D1, H26, K1, M25, R1, V26, AA1, AC25, AF5, AF8, AF19
No Connect (N.C.)	29	6, 7, 8, 9, 11, 12, 13, 15, 16, 17, 18, 109, 140, 141, 142, 144, 145, 146, 147, 149, 150, 151	B6, K19, L2, L4, L18, L19, M1, M2, M3, M4, M16, M17, M18, M19, N1, N2, N3, N4, N16, N17, N18, N19, P1, P2, P3, P17, P18, P19, R1, R2, R3, R17, R18, R19, T1, T2, T3, T17, T18, T19, U1, U2, U3, U17, U18, U19, V1, V2, V19, W1	B4, B5, B6, B7, B8, B9, B11, B12, B13, B14, B15, B16, B18, B19, B20, B21, B22, B23, C4, C23, D4, D23, E4, E22, F4, F23, G4, H4, H23, J23, K4, L4, L23, N4, P4, P23, R3, R26, T2, T3, T4, T5, T22, T23, T24, T25, T26, U3, U4, U5, U22, U23, U24, U25, V2, V3, V4, V5, V22, V23, V24, W1, W2, W3, W4, W5, W22, W23, W24, Y1, Y2, Y3, Y4, Y5, Y22, Y23, Y24, Y25, AA3, AA4, AA5, AA22, AA23, AA24, AA25, AA26, AB2, AB3, AB4, AB5, AB23, AB24, AB25, AC1, AC2, AC23, AD4, AD23, AE4, AE5, AE6, AE7, AE9, AE11, AE12, AE14, AE15, AE16, AE18, AE19, AE20, AE21, AE22, AE23
VPP *(4)*	56	48	C4	E25
Total User I/O Pins *(5)*	60	132	168	168

Notes:
(1) All pins not listed are user I/O pins.
(2) Perform a complete thermal analysis before committing a design to this device package. See *Application Note 74 (Evaluating Power for Altera Devices)*.
(3) EPM9320A devices are not offered in this package.
(4) During in-system programming, each device's VPP pin must be connected to the 5.0-V power supply. During normal device operation, the VPP pin is pulled up internally and can be connected to the 5.0-V supply or left unconnected.
(5) The user I/O pin count includes dedicated input pins and all I/O pins.

Table 27. EPM9400 Dedicated Pin-Outs *Note (1)*

Pin Name	84-Pin PLCC *(2)*	208-Pin RQFP	240-Pin RQFP
DIN1 (GCLK1)	2	182	210
DIN2 (GCLK2)	1	183	211
DIN3 (GCLR)	12	153	187
DIN4 (GOE)	74	4	234
TCK	43	78	91
TMS	54	49	68
TDI	42	79	92
TDO	31	108	114
GND	6, 13, 20, 26, 27, 47, 60, 66, 69, 73	14, 20, 24, 31, 35, 41, 42, 43, 44, 46, 47, 66, 85, 102, 110, 113, 114, 115, 116, 118, 121, 122, 132, 133, 143, 152, 170, 189, 206	5, 14, 25, 34, 45, 54, 65, 66, 81, 96, 110, 115, 126, 127, 146, 147, 166, 167, 186, 200, 216, 229
VCCINT (5.0 V only)	16, 23, 30, 56, 63, 70	10, 19, 30, 45, 112, 128, 139, 148	4, 24, 44, 64, 117, 137, 157, 177
VCCIO (3.3 or 5.0 V)	17, 37, 59, 80	5, 25, 36, 55, 72, 91, 111, 127, 138, 159, 176, 195	15, 35, 55, 73, 86, 101, 116, 136, 156, 176, 192, 205, 220, 235
No Connect (N.C.)	–	6, 7, 8, 9, 11, 12, 13, 109, 144, 145, 146, 147, 149, 150, 151	1, 2, 3, 6, 7, 8, 9, 10, 11, 12, 13, 168, 169, 170, 171, 172, 173, 174, 175, 178, 179, 180, 181, 182, 183, 184, 185, 236, 237, 238, 239, 240
VPP *(3)*	55	48	67
Total User I/O Pins *(4)*	59	139	159

Notes:
(1) All pins not listed are user I/O pins.
(2) Perform a complete thermal analysis before committing a design to this device package. See *Application Note 74 (Evaluating Power for Altera Devices)* for more information.
(3) During in-system programming, each device's VPP pin must be connected to the 5.0-V power supply. During normal device operation, the VPP pin is pulled up internally and can be connected to the 5.0-V supply or left unconnected.
(4) The user I/O pin count includes dedicated input pins and all I/O pins.

Table 28. EPM9480 Dedicated Pin-Outs *Note (1)*

Pin Name	208-Pin RQFP	240-Pin RQFP
DIN1 (GCLK1)	182	210
DIN2 (GCLK2)	183	211
DIN3 (GCLR)	153	187
DIN4 (GOE)	4	234
TCK	78	91
TMS	49	68
TDI	79	92
TDO	108	114
GND	14, 20, 24, 31, 35, 41, 42, 43, 44, 46, 47, 66, 85, 102, 110, 113, 114, 115, 116, 118, 121, 122, 132, 133, 143, 152, 170, 189, 206	5, 14, 25, 34, 45, 54, 65, 66, 81, 96, 110, 115, 126, 127, 146, 147, 166, 167, 186, 200, 216, 229
VCCINT (5.0 V only)	10, 19, 30, 45, 112, 128, 139, 148	4, 24, 44, 64, 117, 137, 157, 177
VCCIO (3.3 or 5.0 V)	5, 25, 36, 55, 72, 91, 111, 127, 138, 159, 176, 195	15, 35, 55, 73, 86, 101, 116, 136, 156, 176, 192, 205, 220, 235
No Connect (N.C.)	6, 7, 8, 9, 109, 149, 150, 151	1, 2, 3, 178, 179, 180, 181, 182, 183, 184, 185, 236, 237, 238, 239, 240
VPP *(2)*	48	67
Total User I/O Pins *(3)*	146	175

Notes:

(1) All pins not listed are user I/O pins.

(2) During in-system programming, each device's VPP pin must be connected to the 5.0-V power supply. During normal device operation, the VPP pin is pulled up internally and can be connected to the 5.0-V supply or left unconnected.

(3) The user I/O pin count includes dedicated input pins and all I/O pins.